Title:	vices ded at uest. rials ecification ocess ess inal PCN expected 2019) for		
Customer Contact: PCN Manager Dept: Quality Service Proposed 1st Ship Date: Nov 13, 2018 Estimated Sample Availability: Date provides Sample required Sample Provides Sample required Sample Sample required Sample Sample required Sample Sampl	rials ecification ocess ess inal PCN expected 2019) for		
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Change Type: Assembly Site Assembly Process Belectrical Specification Change Type: Besign Belectrical Specification Bechanical Specification Change Type: Belectrical Specification Bechanical Specification Change Type: Belectrical Specification Bechanical Specification Bechanical Specification Change Steet Below Wafer Bump Material Wafer Bump Procest Wafer Fab Materials Bescription of Change: Change PCN Details Description of Change: Revision A is to announce the addition of new devices that were not included on the origin notification. These new devices are highlighted and bolded in the device list below. The first shipment date for these new devices will be 90 days from this notice (February 12, 2007) These newly added devices only. The proposed 1st ship date of Nov 13, 2018 still applies for original set of devices. This change notification is to announce the transfer of select devices from ANAM-1 to the Inwafer Fab site. Fab support from ANAM-1 has been discontinued. Buffer inventory has been to cover the notification period of this change notification.	rials ecification ocess ess inal PCN expected 2019) for		
Assembly Site	ocess ess inal PCN expected 2019) for		
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Test Site	inal PCN expected 2019) for		
Wafer Bump Site	inal PCN expected 2019) for		
Wafer Fab Site Part number change PCN Details Description of Change: Revision A is to announce the addition of new devices that were not included on the origin notification. These new devices are highlighted and bolded in the device list below. The first shipment date for these new devices will be 90 days from this notice (February 12, 2) these newly added devices only. The proposed 1st ship date of Nov 13, 2018 still applies for original set of devices. This change notification is to announce the transfer of select devices from ANAM-1 to the I Wafer Fab site. Fab support from ANAM-1 has been discontinued. Buffer inventory has been to cover the notification period of this change notification. Current (Discontinued) New (Transfer to Location)	inal PCN expected 2019) for		
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Current Fab Probe Wafer New Fab Fab Probe)		
	Wafer		
Fab Site Process Site Diameter Site Process Site D	Diameter		
ANAM-1 C10 DBUMP 200mm DMOS5 C10 EBT	200mm		
Reason for Change:			
Discontinued Fab support from ANAM-1			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negati	ive):		
None	,.		
Changes to product identification resulting from this PCN:			
Changes to product identification resulting from this PCN:			
Current:	 1		
Chip Site Chip Site Origin Code Chip Site Country Code (21L) Chip Site	e City		
(ZUL)			
ANAM-1 ANM KOR Bucheor	11-51		
New:			
Chin Site Origin Code			
Chip Site (20L) Chip Site Country Code (21L) Chip Site			
DP1DM5 DM5 USA Dalla:	e City		
2. 22.13			
DI IDRIS DRIS GOA Suma	•		

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS MADE IN: Malaysia

MSL 1 /235C/UNLIM

03/29/04

(1P) SN74LS07NSR

3959047MLA TKY(1T) 7523483SI2

(20L) CSO: SHD (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS

OPT: ITEM:

(L)TO:1750

MSL '2 /260C/1 YEAR SEAL DT

Product Affected:

11000010000			
TLK1211RCP	TLK1221RHATG4	TLK1501IRCPR	TLK2501IRCPG4
TLK1221RHAR	TLK1501IRCP	TLK1501IRCPRG4	TLK2501IRCPR
TLK1221RHARG4	TLK1501IRCPG4	TLK2501IRCP	TLK2501IRCPRG4
TI K1221DHAT			

Qualification Report

Approve Date 24-July-2018

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TLK1501IRCP	QBS Process Reference: TLK2500IRCP	QBS Package Reference: TLK2201BIRCP
AC	Autoclave 121C, 2atm	96 Hours	-	3/231/0	3/231/0
CDM	ESD - CDM	1000 V	1/3/0	-	-
ED	Electrical Characterization	Per Data Sheet Parameters	Pass	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-
HBM	ESD - HBM	4000 V	1/3/0	-	-
HTOL	Life Test, 155C	240 Hours	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	3/135/0	3/135/0
LU	Latch-up	(Per JESD78)	1/6/0	-	-
T/C	Temp Cycle -65C/150C	500 Cycles	-	-	3/231/0

- QBS: Qual By Similarity
- Qual Device TLK1501IRCP is qualified at LEVEL3-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Report

Approve Date 24-July-2018

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TLK2501IRCP	QBS Process Reference: TLK2500IRCP	QBS Package Reference: TLK2201BIRCP
AC	Autoclave 121C, 2atm	96 Hours	-	3/231/0	3/231/0
CDM	ESD - CDM	1000 V	1/3/0	-	-
ED	Electrical Characterization	Per Data Sheet Parameters	Pass	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-
HBM	ESD - HBM	4000 V	1/3/0	-	-
HTOL	Life Test, 155C	240 Hours	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	3/135/0	3/135/0
LU	Latch-up	(Per JESD78)	1/6/0	-	-
T/C	Temp Cycle -65C/150C	500 Cycles	-	-	3/231/0

- QBS: Qual By Similarity
- Qual Device TLK2501IRCP is qualified at LEVEL3-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
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Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com